

USE INSTRUCTIONS



SPI Supplies
206 Garfield Avenue,
West Chester, PA 19380, USA

Use Instructions for Wafer-Mount™ 562

1. Cut the Wafer-Mount™ sheet to the desired shape and size, and position on a ceramic or glass mounting plate. Use multiple preforms as required to fill in small cavities or gaps caused by warping of the substrate.
2. Using a hot plate or oven, heat the mounting plate to 195-210 °F. Make sure to work in a well-ventilated area, and do not overshoot the flow temperature, otherwise, the adhesive will begin to decompose and degrade in strength.
3. Using a weight, apply even pressure to the substrate to remove air bubbles and to ensure that the substrate is parallel to the plate.
4. Remove the mounting plate from the heat source and allow it to cool slowly to room temperature until the adhesive is hardened. Cool for 20-30 minutes prior to processing.
5. Process the substrate as required, then remove parts by re-heating the mounting block to the flow temperature. Use a tool to slide the substrate off the mounting plate.
6. For detailed cleaning procedures, refer to the section describing the 562-S Stripper.

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